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FDBL0330N80

# N-Channel PowerTrench<sup>®</sup> MOSFET 80 V, 220 A, 3.0 m $\Omega$

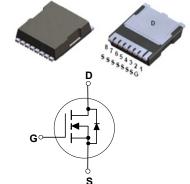
#### **Features**

- Typical  $R_{DS(on)}$  = 2.4 mΩ at  $V_{GS}$  = 10V,  $I_D$  = 80 A
- Typical  $Q_{q(tot)}$  = 86 nC at  $V_{GS}$  = 10V,  $I_D$  = 80 A
- UIS Capability
- RoHS Compliant

#### **Applications**

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automations
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





**April 2015** 

For current package drawing, please refer to the Fairchild website at http://www.fairchildsemi.com/dwg/PS/PSOF08A.pdf.

### **MOSFET Maximum Ratings** $T_J = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Ratings	Units	
$V_{DSS}$	Drain-to-Source Voltage		80	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous ( $V_{GS}$ =10) (Note 1) $T_C$ = 25°C		220	^
ID	Pulsed Drain Current	T <sub>C</sub> = 25°C	See Figure 4	A
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 2)	205	mJ
D	Power Dissipation		300	W
$P_{D}$	Derate Above 25°C		2.0	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.5	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

#### Notes

- Current is limited by silicon.
- 2: Starting T<sub>J</sub> = 25°C, L = 0.1mH, I<sub>AS</sub> = 64A, V<sub>DD</sub> = 80V during inductor charging and V<sub>DD</sub> = 0V during time in avalanche.
- 3: R<sub>0,JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>0,JC</sub> is guaranteed by design, while R<sub>0,JA</sub> is determined by the board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0330N80	FDBL0330N80	MO-299A	-	-	-

Units

Max.

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted.

**Parameter** 

Off Characteristics							
B <sub>VDSS</sub>	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	80	-	-	V	
ı	Drain-to-Source Leakage Current	$V_{DS} = 80V$ , $T_{J} = 25^{\circ}$	C -	-	1	μА	
DSS		$V_{GS} = 0V$ $T_J = 175$	°C (Note 4) -	-	1	mA	
I <sub>GSS</sub>	Gate-to-Source Leakage Current	V <sub>GS</sub> = ±20V	-	-	±100	nA	

**Test Conditions** 

Min.

Тур.

#### On Characteristics

Symbol

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	٧
D	Drain to Source On Resistance	I <sub>D</sub> = 80A,	$T_{J} = 25^{\circ}C$	-	2.4	3.0	$m\Omega$
R <sub>DS(on)</sub>		V <sub>GS</sub> = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	ı	4.9	6.1	$m\Omega$

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V, f = 1MHz		-	6320	-	pF
C <sub>oss</sub>	Output Capacitance			-	1030	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			-	32	-	pF
$R_g$	Gate Resistance	f = 1MHz		-	2.1	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0 to 10V	V <sub>DD</sub> = 64V	-	86	112	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		-	12	18	nC
$Q_{gs}$	Gate-to-Source Gate Charge		_	-	30	-	nC
$Q_{gd}$	Gate-to-Drain "Miller" Charge			-	18	-	nC

# **Switching Characteristics**

t <sub>on</sub>	Turn-On Time	$V_{DD}$ = 40V, $I_{D}$ = 80A, $V_{GS}$ = 10V, $R_{GEN}$ = 6 $\Omega$	-	-	98	ns
t <sub>d(on)</sub>	Turn-On Delay		-	30	-	ns
t <sub>r</sub>	Rise Time		-	34	-	ns
t <sub>d(off)</sub>	Turn-Off Delay		-	40	-	ns
t <sub>f</sub>	Fall Time		-	17	-	ns
t <sub>off</sub>	Turn-Off Time		-	ı	86	ns

#### **Drain-Source Diode Characteristics**

$V_{SD}$	I Source-to-Drain Dioge Voltage	I <sub>SD</sub> =80A, V <sub>GS</sub> = 0V	-	-	1.25	V
		$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	٧
t <sub>rr</sub>	Reverse-Recovery Time	$I_F = 80A$ , $dI_{SD}/dt = 100A/\mu s$ ,	-	80	120	ns
Q <sub>rr</sub>	Reverse-Recovery Charge	V <sub>DD</sub> =64V	-	95	140	nC

#### Note

4: The maximum value is specified by design at  $T_J$  = 175°C. Product is not tested to this condition in production.

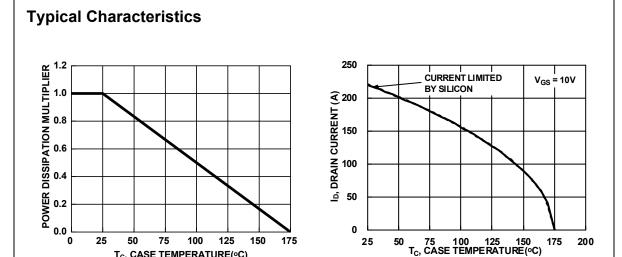


Figure 1. Normalized Power Dissipation vs. Case **Temperature** 

T<sub>C</sub>, CASE TEMPERATURE(°C)

Figure 2. Maximum Continuous Drain Current vs. **Case Temperature** 

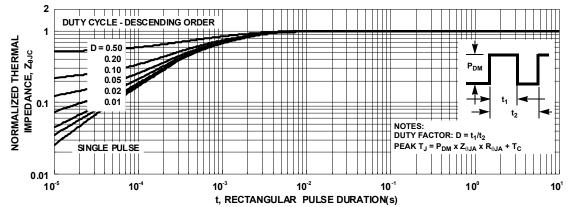


Figure 3. Normalized Maximum Transient Thermal Impedance

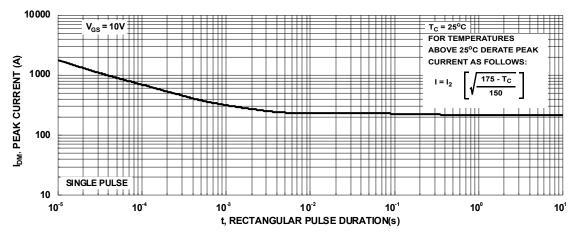


Figure 4. Peak Current Capability

# **Typical Characteristics**

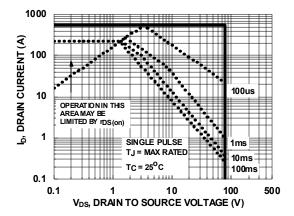
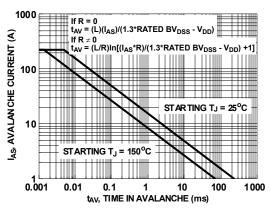


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

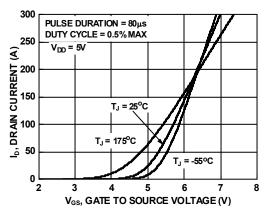


Figure 7. Transfer Characteristics

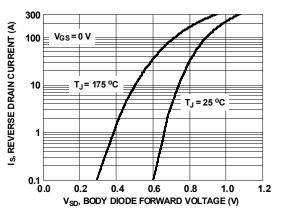


Figure 8. Forward Diode Characteristics

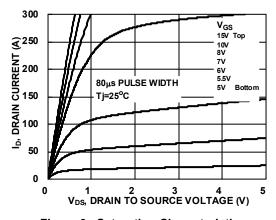


Figure 9. Saturation Characteristics

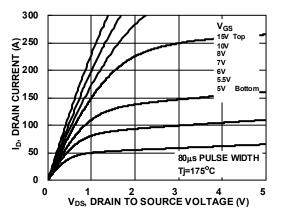


Figure 10. Saturation Characteristics

# **Typical Characteristics**

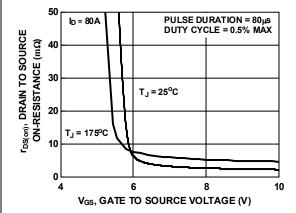


Figure 11. R<sub>DSON</sub> vs. Gate Voltage

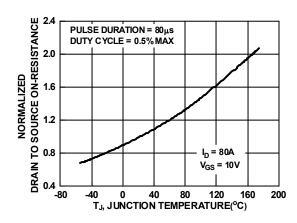


Figure 12. Normalized R<sub>DSON</sub> vs. Junction Temperature

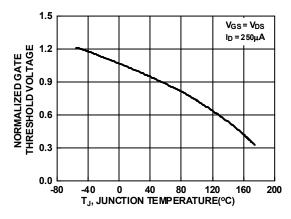


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

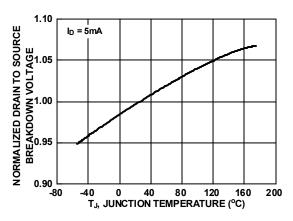


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

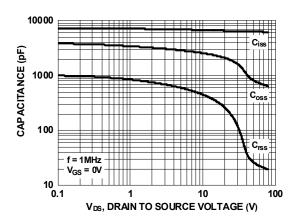


Figure 15. Capacitance vs. Drain to Source Voltage

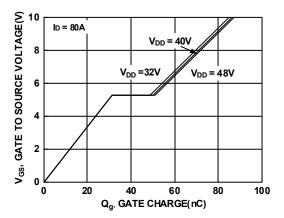
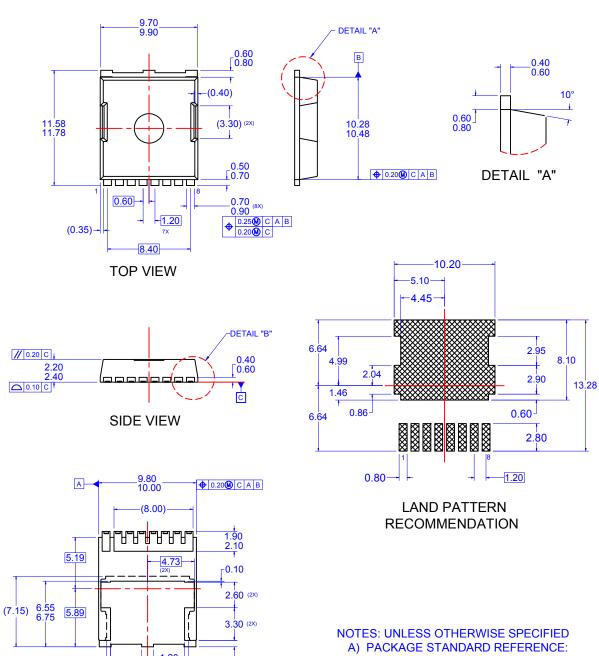


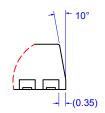
Figure 16. Gate Charge vs. Gate to Source Voltage



- JEDEC MO-299, ISSUE A, DATED NOVEMBER
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

- - 1.20 0.65-3.75 7.60 -(8.30)

**BOTTOM VIEW** 



DETAIL "B"

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